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**STM32F411xC and STM32F411xE device limitations**

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**Silicon identification**

This errata sheet applies to STMicroelectronics STM32F411xC and STM32F411xE microcontrollers.

The STM32F411xC and STM32F411xE devices feature an ARM® 32-bit Cortex®-M4 core with FPU, for which an errata notice is also available (see [Section 1](#) for details).

The full list of part numbers is shown in [Table 2](#). The products are identifiable as shown in [Table 1](#):

- by the revision code marked below the order code on the device package
- by the last three digits of the Internal order code printed on the box label

**Table 1. Device identification<sup>(1)</sup>**

Order code	Revision code marked on device <sup>(2)</sup>
STM32F411xC, STM32F411xE	"A"

1. The REV\_ID bits in the DBGMCU\_IDCODE register show the revision code of the device (see the RM0383 STM32F411xx reference manual for details on how to find the revision code).
2. Refer to datasheet for the device marking.

**Table 2. Device summary**

Reference	Part number
STM32F411xC	STM32F411CC, STM32F411RC, STM32F411VC
STM32F411xE	STM32F411CE, STM32F411RE, STM32F411VE

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# 1 ARM 32-bit Cortex-M4 with FPU limitations

An errata notice of the STM32F411xC and STM32F411xE core is available from <http://infocenter.arm.com>.

All the described limitations are minor and related to the revision r0p1-v1 of the Cortex-M4 core. [Table 3](#) summarizes these limitations and their implications on the behavior of STM32F411xC and STM32F411xE devices.

**Table 3. Cortex-M4 core limitations and impact on microcontroller behavior**

ARM ID	ARM category	ARM summary of errata	Impact on STM32F411xC and STM32F411xE
752770	Cat B	Interrupted loads to SP can cause erroneous behavior	Minor
776924	Cat B	VDIV or VSQRT instructions might not complete correctly when very short ISRs are used	Minor

## 1.1 Cortex-M4 interrupted loads to stack pointer can cause erroneous behavior

### Description

An interrupt occurring during the data-phase of a single word load to the stack pointer (SP/R13) can cause an erroneous behavior of the device. In addition, returning from the interrupt results in the load instruction being executed an additional time.

For all the instructions performing an update of the base register, the base register is erroneously updated on each execution, resulting in the stack pointer being loaded from an incorrect memory location.

The instructions affected by this limitation are the following:

- LDR SP, [Rn],#imm
- LDR SP, [Rn,#imm]!
- LDR SP, [Rn,#imm]
- LDR SP, [Rn]
- LDR SP, [Rn,Rm]

### Workaround

As of today, no compiler generates these particular instructions. This limitation can only occur with hand-written assembly code.

Both limitations can be solved by replacing the direct load to the stack pointer by an intermediate load to a general-purpose register followed by a move to the stack pointer.

Example:

Replace LDR SP, [R0] by

```
LDR R2,[R0]
```

```
MOV SP,R2
```

## 1.2 VDIV or VSQRT instructions might not complete correctly when very short ISRs are used

### Description

On Cortex-M4 with FPU core, 14 cycles are required to execute a VDIV or VSQRT instruction.

This limitation is present when the following conditions are met:

- A VDIV or VSQRT is executed
- The destination register for VDIV or VSQRT is one of s0 - s15
- An interrupt occurs and is taken
- The ISR being executed does not contain a floating point instruction
- 14 cycles after the VDIV or VSQRT is executed, an interrupt return is executed

In this case, if there are only one or two instructions inside the interrupt service routine, then the VDIV or VSQRT instruction does not complete correctly and the register bank and FPSCR are not updated, meaning that these registers hold incorrect out-of-date data.

### Workaround

Two workarounds are applicable:

- Disable lazy context save of floating point state by clearing LSPEN to 0 (bit 30 of the FPCCR at address 0xE000EF34).
- Ensure that every ISR contains more than 2 instructions in addition to the exception return instruction.

## 2 STM32F411xC and STM32F411xE silicon limitations

[Table 4](#) gives quick references to all documented limitations.

Legend for [Table 4](#): A = workaround available; N = no workaround available; P = partial workaround available, '-' and grayed = fixed.

**Table 4. Summary of silicon limitations**

Links to silicon limitations		Revision A
Section 2.1: System limitations	<a href="#">Section 2.1.1: Debugging Stop mode and system tick timer</a>	A
	<a href="#">Section 2.1.2: Debugging Stop mode with WFE entry</a>	A
	<a href="#">Section 2.1.3: Wakeup sequence from Standby mode when using more than one wakeup source</a>	A
	<a href="#">Section 2.1.4: Full JTAG configuration without NJTRST pin cannot be used</a>	A
	<a href="#">Section 2.1.5: MPU attribute to RTC and IWDG registers could be managed incorrectly</a>	A
	<a href="#">Section 2.1.6: Delay after an RCC peripheral clock enabling</a>	A
	<a href="#">Section 2.1.7: PB5 I/O limitation for externally applied voltage</a>	A
	<a href="#">Section 2.1.8: PA0 I/O VIN limitation in Standby mode</a>	A
	<a href="#">Section 2.1.9: PH1 cannot be used as a GPIO in HSE bypass mode</a>	N
	<a href="#">Section 2.1.10: In some specific cases, DMA2 data corruption occurs when managing AHB and APB2 peripherals in a concurrent way</a>	A
Section 2.2: IWDG peripheral limitation	<a href="#">Section 2.2.1: RVU and PVU flags are not reset in STOP mode</a>	A
Section 2.3: I2C peripheral limitations	<a href="#">Section 2.3.1: SMBus standard not fully supported</a>	A
	<a href="#">Section 2.3.2: Start cannot be generated after a misplaced Stop</a>	A
	<a href="#">Section 2.3.3: Mismatch on the "Setup time for a repeated Start condition" timing parameter</a>	A
	<a href="#">Section 2.3.4: Data valid time (tVD;DAT) violated without the OVR flag being set</a>	A
	<a href="#">Section 2.3.5: Both SDA and SCL maximum rise time (tr) violated when VDD_I2C bus higher than ((VDD+0.3) / 0.7) V</a>	A
Section 2.4: I2S peripheral limitation	<a href="#">Section 2.4.1: In I2S slave mode, WS level must be set by the external master when enabling the I2S</a>	A
	<a href="#">Section 2.4.2: Corrupted last bit of data and/or CRC, received in Master mode with delayed SCK feedback</a>	A

Table 4. Summary of silicon limitations (continued)

Links to silicon limitations		Revision A
Section 2.5: USART peripheral limitations	Section 2.5.1: Idle frame is not detected if receiver clock speed is deviated	N
	Section 2.5.2: In full duplex mode, the Parity Error (PE) flag can be cleared by writing to the data register	A
	Section 2.5.3: Parity Error (PE) flag is not set when receiving in Mute mode using address mark detection	N
	Section 2.5.4: Break frame is transmitted regardless of nCTS input line status	N
	Section 2.5.5: nRTS signal abnormally driven low after a protocol violation	A
Section 2.6: OTG_FS peripheral limitations	Section 2.6.1: Data in RxFIFO is overwritten when all channels are disabled simultaneously	A
	Section 2.6.2: OTG host blocks the receive channel when receiving IN packets and no TxFIFO is configured	A
	Section 2.6.3: Host channel-halted interrupt not generated when the channel is disabled	A
	Section 2.6.4: Error in software-read OTG_FS_DCFG register values	A
Section 2.7: SDIO peripheral limitations	Section 2.7.1: SDIO HW flow control	N
	Section 2.7.2: Wrong CCRCFAIL status after a response without CRC is received	A
	Section 2.7.3: Data corruption in SDIO clock dephasing (NEGEDGE) mode	N
	Section 2.7.4: CE-ATA multiple write command and card busy signal management	A
	Section 2.7.5: No underrun detection with wrong data transmission	A
Section 2.8: ADC peripheral limitations	Section 2.8.1: ADC sequencer modification during conversion	A
Section 2.9: SPI peripheral limitations	Section 2.9.1: BSY bit may stay high at the end of a data transfer in Slave mode	A
	Section 2.9.2: Corrupted last bit of data and/or CRC, received in Master mode with delayed SCK feedback	A
	Section 2.9.3: Wrong CRC calculation when the polynomial is even.	A



## 2.1 System limitations

### 2.1.1 Debugging Stop mode and system tick timer

#### Description

If the system tick timer interrupt is enabled during the Stop mode debug (DBG\_STOP bit set in the DBGMCU\_CR register), it will wake up the system from Stop mode.

#### Workaround

To debug the Stop mode, disable the system tick timer interrupt.

### 2.1.2 Debugging Stop mode with WFE entry

#### Description

When the Stop debug mode is enabled (DBG\_STOP bit set in the DBGMCU\_CR register), this allows software debugging during Stop mode.

However, if the application software uses the WFE instruction to enter Stop mode, after wakeup some instructions could be missed if the WFE is followed by sequential instructions. This affects only Stop debug mode with WFE entry.

#### Workaround

To debug Stop mode with WFE entry, the WFE instruction must be inside a dedicated function with 1 instruction (NOP) between the execution of the WFE and the Bx LR.

Example:

```
__asm void _WFE(void) {  
    WFE  
    NOP  
    BX LR }  
}
```

### 2.1.3 Wakeup sequence from Standby mode when using more than one wakeup source

#### Description

The various wakeup sources are logically OR-ed in front of the rising-edge detector which generates the wakeup flag (WUF). The WUF needs to be cleared prior to Standby mode entry, otherwise the MCU wakes up immediately.

If one of the configured wakeup sources is kept high during the clearing of the WUF (by setting the CWUF bit), it may mask further wakeup events on the input of the edge detector. As a consequence, the MCU might not be able to wake up from Standby mode.

**Workaround**

To avoid this problem, the following sequence should be applied before entering Standby mode:

- Disable all used wakeup sources,
- Clear all related wakeup flags,
- Re-enable all used wakeup sources,
- Enter Standby mode

*Note: Be aware that, when applying this workaround, if one of the wakeup sources is still kept high, the MCU enters Standby mode but then it wakes up immediately generating a power reset.*

**2.1.4 Full JTAG configuration without NJTRST pin cannot be used****Description**

When using the JTAG debug port in debug mode, the connection with the debugger is lost if the NJTRST pin (PB4) is used as a GPIO. Only the 4-wire JTAG port configuration is impacted.

**Workaround**

Use the SWD debug port instead of the full 4-wire JTAG port.

**2.1.5 MPU attribute to RTC and IWDG registers could be managed incorrectly****Description**

If the MPU is used and the non bufferable attribute is set to the RTC or IWDG memory map region, the CPU access to the RTC or IWDG registers could be treated as bufferable, provided that there is no APB prescaler configured (AHB/APB prescaler is equal to 1).

**Workaround**

If the non bufferable attribute is required for these registers, the software could perform a read after the write to guaranty the completion of the write access.

**2.1.6 Delay after an RCC peripheral clock enabling****Description**

A delay between an RCC peripheral clock enable and the effective peripheral enabling should be taken into account in order to manage the peripheral read/write to registers.

This delay depends on the peripheral mapping:

- If the peripheral is mapped on AHB: the delay should be equal to 2 AHB clock cycles after the clock enable bit is set in the hardware register.
- If the peripheral is mapped on APB: the delay should be equal to 2 APB clock cycles after the clock enable bit is set in the hardware register.

**Workarounds**

1. Enable the peripheral clock some time before the peripheral read/write register is required.
2. For AHB peripheral, insert two dummy read operations to the peripheral register.
3. For APB peripheral, insert a dummy read operations to the peripheral register.

**2.1.7 PB5 I/O limitation for externally applied voltage****Description**

If an externally applied voltage on PB5 exceeds  $V_{DD}$  supply voltage, an I/O leakage current, which can impact the product lifetime, is observed.

**Workaround**

There is no functional limitation on PB5 pad if  $V_{IN}$  does not exceed  $V_{DD}$ .

**2.1.8 PA0 I/O  $V_{IN}$  limitation in Standby mode****Description**

In Standby mode, if the input voltage ( $V_{IN}$ ) applied to PA0 exceeds  $V_{DD}$  supply voltage, an I/O leakage current, which can impact the product lifetime, is observed.

**Workaround**

There is no functional limitation on PA0 pad if  $V_{IN}$  does not exceed  $V_{DD}$ .

If the device does not operate in Standby mode, PA0 is 5 V tolerant (FT) thus allowing an input voltage higher than  $V_{DD}$  (according to the datasheet specifications).

**2.1.9 PH1 cannot be used as a GPIO in HSE bypass mode****Description**

When an external clock is used and the HSE is bypassed, PH1 cannot be used as GPIO.

**Workaround**

None.

**2.1.10 In some specific cases, DMA2 data corruption occurs when managing AHB and APB2 peripherals in a concurrent way****Description**

When the DMA2 is managing concurrent requests of AHB and APB2 peripherals, the transfer of the AHB could be performed several times.

The impacted peripherals is:

- **GPIO:** specifically the DMA2 transfers to the GPIO registers (in memory-to-peripheral transfer mode). The transfers from the GPIOs register are not impacted.

The data corruption is due to multiple DMA2 accesses over the AHP peripheral port, impacting peripherals embedding a FIFO.

For transfers to the internal SRAM through the DMA2 AHB peripheral port, the accesses could be performed several times, but without data corruptions in cases of concurrent requests.

### Workaround

The DMA2 AHB memory port must be used when writing to the GPIOs instead of the DMA2 AHB default peripheral port.

For more details on the DMA controller feature, refer to the section “Take benefits of DMA2 controller and system architecture flexibility” of the application note *Using the STM32F2, STM32F4 and STM32F7 Series DMA controller* (AN4031) available at STMicroelectronics website.

## 2.2 IWDG peripheral limitation

### 2.2.1 RVU and PVU flags are not reset in STOP mode

#### Description

The RVU and PVU flags of the IWDG\_SR register are set by hardware after a write access to the IWDG\_RLR and the IWDG\_PR registers, respectively. If the Stop mode is entered immediately after the write access, the RVU and PVU flags are not reset by hardware.

Before performing a second write operation to the IWDG\_RLR or the IWDG\_PR register, the application software must wait for the RVU or PVU flag to be reset. However, since the RVU/PVU bit is not reset after exiting the Stop mode, the software goes into an infinite loop and the independent watchdog (IWDG) generates a reset after the programmed timeout period.

### Workaround

Wait until the RVU or PVU flag of the IWDG\_SR register is reset before entering the Stop mode.

## 2.3 I2C peripheral limitations

### 2.3.1 SMBus standard not fully supported

#### Description

The I<sup>2</sup>C peripheral is not fully compliant with the SMBus v2.0 standard since It does not support the capability to NACK an invalid byte/command.

### Workarounds

A higher-level mechanism should be used to verify that a write operation is being performed correctly at the target device, such as:

1. Using the SMBAL pin if supported by the host
2. the alert response address (ARA) protocol
3. the Host notify protocol

### 2.3.2 Start cannot be generated after a misplaced Stop

#### Description

If a master generates a misplaced Stop on the bus (bus error), the peripheral cannot generate a Start anymore.

#### Workaround

In the I<sup>2</sup>C standard, it is allowed to send a Stop only at the end of the full byte (8 bits + acknowledge), so this scenario is not allowed. Other derived protocols like CBUS allow it, but they are not supported by the I<sup>2</sup>C peripheral.

A software workaround consists in asserting the software reset using the SWRST bit in the I2C\_CR1 control register.

### 2.3.3 Mismatch on the “Setup time for a repeated Start condition” timing parameter

#### Description

In case of a repeated Start, the “Setup time for a repeated Start condition” (named  $T_{su;sta}$  in the I<sup>2</sup>C specification) can be slightly violated when the I<sup>2</sup>C operates in Master Standard mode at a frequency between 88 kHz and 100 kHz.

The limitation can occur only in the following configuration:

- in Master mode
- in Standard mode at a frequency between 88 kHz and 100 kHz (no limitation in Fast-mode)
- SCL rise time:
  - If the slave does not stretch the clock and the SCL rise time is more than 300 ns (if the SCL rise time is less than 300 ns, the limitation cannot occur)
  - If the slave stretches the clock

The setup time can be violated independently of the APB peripheral frequency.

#### Workaround

Reduce the frequency down to 88 kHz or use the I<sup>2</sup>C Fast-mode, if supported by the slave.

### 2.3.4 Data valid time ( $t_{VD;DAT}$ ) violated without the OVR flag being set

#### Description

The data valid time ( $t_{VD;DAT}$ ,  $t_{VD;ACK}$ ) described by the I<sup>2</sup>C standard can be violated (as well as the maximum data hold time of the current data ( $t_{HD;DAT}$ )) under the conditions described below. This violation cannot be detected because the OVR flag is not set (no transmit buffer underrun is detected).

This limitation can occur only under the following conditions:

- in Slave transmit mode
- with clock stretching disabled (NOSTRETCH=1)
- if the software is late to write the DR data register, but not late enough to set the OVR flag (the data register is written before)

#### Workaround

If the master device allows it, use the clock stretching mechanism by programming the bit NOSTRETCH=0 in the I2C\_CR1 register.

If the master device does not allow it, ensure that the software is fast enough when polling the TXE or ADDR flag to immediately write to the DR data register. For instance, use an interrupt on the TXE or ADDR flag and boost its priority to the higher level.

### 2.3.5 Both SDA and SCL maximum rise time ( $t_r$ ) violated when VDD\_I2C bus higher than $((V_{DD}+0.3) / 0.7)$ V

#### Description

When an external legacy I<sup>2</sup>C bus voltage (VDD\_I2C) is set to 5 V while the MCU is powered from V<sub>DD</sub>, the internal 5-Volt tolerant circuitry is activated as soon the input voltage (V<sub>IN</sub>) reaches the V<sub>DD</sub> + diode threshold level. An additional internal large capacitance then prevents the external pull-up resistor (R<sub>P</sub>) from rising the SDA and SCL signals within the maximum timing ( $t_r$ ) which is 300 ns in fast mode and 1000 ns in Standard mode.

The rise time ( $t_r$ ) is measured from V<sub>IL</sub> and V<sub>IH</sub> with levels set at 0.3VDD\_I2C and 0.7VDD\_I2C.

#### Workaround

The external VDD\_I2C bus voltage should be limited to a maximum value of  $((V_{DD}+0.3) / 0.7)$  V. As a result, when the MCU is powered from V<sub>DD</sub>=3.3 V, VDD\_I2C should not exceed 5.14 V to be compliant with I<sup>2</sup>C specifications.

## 2.4 I2S peripheral limitation

### 2.4.1 In I2S slave mode, WS level must be set by the external master when enabling the I2S

#### Description

In slave mode, the WS signal level is used only to start the communication. If the I2S (in slave mode) is enabled while the master is already sending the clock and the WS signal level is low (for I2S protocol) or is high (for the LSB or MSB-justified mode), the slave starts communicating data immediately. In this case, the master and slave will be desynchronized throughout the whole communication.

**Workaround**

The I2S peripheral must be enabled when the external master sets the WS line at:

- High level when the I2S protocol is selected.
- Low level when the LSB or MSB-justified mode is selected.

**2.4.2 Corrupted last bit of data and/or CRC, received in Master mode with delayed SCK feedback**

The limitation described in [Section 2.9.2: Corrupted last bit of data and/or CRC, received in Master mode with delayed SCK feedback](#) also applies to I<sup>2</sup>S interface.

**2.5 USART peripheral limitations****2.5.1 Idle frame is not detected if receiver clock speed is deviated****Description**

If the USART receives an idle frame followed by a character, and the clock of the transmitter device is faster than the USART receiver clock, the USART receive signal falls too early when receiving the character start bit, with the result that the idle frame is not detected (IDLE flag is not set).

**Workaround**

None.

**2.5.2 In full duplex mode, the Parity Error (PE) flag can be cleared by writing to the data register****Description**

In full duplex mode, when the Parity Error flag is set by the receiver at the end of a reception, it may be cleared while transmitting by reading the USART\_SR register to check the TXE or TC flags and writing data to the data register.

Consequently, the software receiver can read the PE flag as '0' even if a parity error occurred.

**Workaround**

The Parity Error flag should be checked after the end of reception and before transmission.

**2.5.3 Parity Error (PE) flag is not set when receiving in Mute mode using address mark detection****Description**

The USART receiver is in Mute mode and is configured to exit the Mute mode using the address mark detection. When the USART receiver recognizes a valid address with a parity error, it exits the Mute mode without setting the Parity Error flag.

**Workaround**

None.

**2.5.4 Break frame is transmitted regardless of nCTS input line status****Description**

When CTS hardware flow control is enabled (CTSE = 1) and the Send Break bit (SBK) is set, the transmitter sends a break frame at the end of the current transmission regardless of nCTS input line status.

Consequently, if an external receiver device is not ready to accept a frame, the transmitted break frame is lost.

**Workaround**

None.

**2.5.5 nRTS signal abnormally driven low after a protocol violation****Description**

When RTS hardware flow control is enabled, the nRTS signal goes high when data is received. If this data was not read and new data is sent to the USART (protocol violation), the nRTS signal goes back to low level at the end of this new data.

Consequently, the sender gets the wrong information that the USART is ready to receive further data.

On USART side, an overrun is detected, which indicates that data has been lost.

**Workaround**

Workarounds are required only if the other USART device violates the communication protocol, which is not the case in most applications.

Two workarounds can be used:

- After data reception and before reading the data in the data register, the software takes over the control of the nRTS signal as a GPIO and holds it high as long as needed. If the USART device is not ready, the software holds the nRTS pin high, and releases it when the device is ready to receive new data.
- The time required by the software to read the received data must always be lower than the duration of the second data reception. For example, this can be ensured by treating all the receptions by DMA mode.



## 2.6 OTG\_FS peripheral limitations

### 2.6.1 Data in RxFIFO is overwritten when all channels are disabled simultaneously

#### Description

If the available RxFIFO is just large enough to host 1 packet + its data status, and is currently occupied by the last received data + its status and, at the same time, the application requests that more IN channels be disabled, the OTG\_FS peripheral does not first check for available space before inserting the disabled status of the IN channels. It just inserts them by overwriting the existing data payload.

#### Workaround

Use one of the following recommendations:

1. Configure the RxFIFO to host a *minimum* of  $2 \times \text{MPSIZ} + 2 \times \text{data status entries}$ .
2. The application has to check the RXFLVL bit (RxFIFO non-empty) in the OTG\_FS\_GINTSTS register before disabling each IN channel. If this bit is not set, then the application can disable an IN channel at a time. Each time the application disables an IN channel, however, it first has to check that the RXFLVL bit = 0 condition is true.

### 2.6.2 OTG host blocks the receive channel when receiving IN packets and no Tx FIFO is configured

#### Description

When receiving data, the OTG\_FS core erroneously checks for available Tx FIFO space when it should only check for RxFIFO space. If the OTG\_FS core cannot see any space allocated for data transmission, it blocks the reception channel and no data is received.

#### Workaround

Set at least one Tx FIFO equal to the maximum packet size. In this way, the host application, which intends to support only IN traffic, also has to allocate some space for the Tx FIFO.

Since a USB host is expected to support any kind of connected endpoint, it is good practice to always configure enough Tx FIFO space for OUT endpoints.

### 2.6.3 Host channel-halted interrupt not generated when the channel is disabled

#### Description

When the application enables, then immediately disables the host channel before the OTG\_FS host has had time to begin the transfer sequence, the OTG\_FS core, as a host, does not generate a channel-halted interrupt. The OTG\_FS core continues to operate normally.

#### Workaround

Do not disable the host channel immediately after enabling it.

## 2.6.4 Error in software-read OTG\_FS\_DCFG register values

### Description

When the application writes to the DAD and PFIVL bitfields in the OTG\_FS\_DCFG register, and then reads the newly written bitfield values, the read values may not be correct.

The values written by the application, however, are correctly retained by the core, and the normal operation of the device is not affected.

### Workaround

Do not read from the OTG\_FS\_DCFG register's DAD and PFIVL bitfields just after programming them.

## 2.7 SDIO peripheral limitations

### 2.7.1 SDIO HW flow control

#### Description

When enabling the HW flow control by setting bit 14 of the SDIO\_CLKCR register to '1', glitches can occur on the SDIOCLK output clock resulting in wrong data to be written into the SD/MMC card or into the SDIO device. As a consequence, a CRC error will be reported to the SD/SDIO MMC host interface (DCRCFAIL bit set to '1' in SDIO\_STA register).

#### Workaround

None.

*Note: Do not use the HW flow control. Overrun errors (Rx mode) and FIFO underrun (Tx mode) should be managed by the application software.*

### 2.7.2 Wrong CCRCFAIL status after a response without CRC is received

#### Description

The CRC is calculated even if the response to a command does not contain any CRC field. As a consequence, after the SDIO command IO\_SEND\_OP\_COND (CMD5) is sent, the CCRCFAIL bit of the SDIO\_STA register is set.

#### Workaround

The CCRCFAIL bit in the SDIO\_STA register shall be ignored by the software. CCRCFAIL must be cleared by setting CCRCFAILC bit of the SDIO\_ICR register after reception of the response to the CMD5 command.

### 2.7.3 Data corruption in SDIO clock dephasing (NEGEDGE) mode

#### Description

When NEGEDGE bit is set to '1', it may lead to invalid data and command response read.

**Workaround**

None. A configuration with the NEGEDGE bit equal to '1' should not be used.

**2.7.4 CE-ATA multiple write command and card busy signal management****Description**

The CE-ATA card may inform the host that it is busy by driving the SDIO\_D0 line low, two cycles after the transfer of a write command (RW\_MULTIPLE\_REGISTER or RW\_MULTIPLE\_BLOCK). When the card is in a busy state, the host must not send any data until the BUSY signal is de-asserted (SDIO\_D0 released by the card).

This condition is not respected if the data state machine leaves the IDLE state (Write operation programmed and started, DTEN = 1, DTDIR = 0 in SDIO\_DCTRL register and TXFIFOE = 0 in SDIO\_STA register).

As a consequence, the write transfer fails and the data lines are corrupted.

**Workaround**

After sending the write command (RW\_MULTIPLE\_REGISTER or RW\_MULTIPLE\_BLOCK), the application must check that the card is not busy by polling the BSY bit of the ATA status register using the FAST\_IO (CMD39) command before enabling the data state machine.

**2.7.5 No underrun detection with wrong data transmission****Description**

In case there is an ongoing data transfer from the SDIO host to the SD card and the hardware flow control is disabled (bit 14 of the SDIO\_CLKCR is not set), if an underrun condition occurs, the controller may transmit a corrupted data block (with wrong data word) without detecting the underrun condition when the clock frequencies have the following relationship:

$$[3 \times \text{period}(\text{PCLK2}) + 3 \times \text{period}(\text{SDIOCLK})] \geq (32 / (\text{BusWidth})) \times \text{period}(\text{SDIO\_CK})$$

**Workaround**

Avoid the above-mentioned clock frequency relationship, by:

- Incrementing the APB frequency
- or decreasing the transfer bandwidth
- or reducing SDIO\_CK frequency

## 2.8 ADC peripheral limitations

### 2.8.1 ADC sequencer modification during conversion

#### Description

If an ADC conversion is started by software (writing the SWSTART bit), and if the ADC\_SQRx or ADC\_JSQRx registers are modified during the conversion, the current conversion is reset and the ADC does not restart a new conversion sequence automatically.

If an ADC conversion is started by hardware trigger, this limitation does not apply. The ADC restarts a new conversion sequence automatically.

#### Workaround

When an ADC conversion sequence is started by software, a new conversion sequence can be restarted only by setting the SWSTART bit in the ADC\_CR2 register.

## 2.9 SPI peripheral limitations

### 2.9.1 BSY bit may stay high at the end of a data transfer in Slave mode

#### Description

The BSY flag may sporadically remain high at the end of a data transfer in Slave mode. The issue appears when an accidental synchronization happens between the internal CPU clock and the external SCK clock provided by master.

This is related to the end of data transfer detection while the SPI is enabled in Slave mode.

As a consequence, the end of data transaction may not be recognized when the software needs to monitor it (for example at the end of a session before entering the low-power mode or before the direction of data line has to be changed at half duplex bidirectional mode). The BSY flag is unreliable to detect the end of any data sequence transaction.

#### Workaround

When NSS hardware management is applied and NSS signal is provided by master, the end of a transaction can be detected by the NSS polling by slave.

- If SPI receiving mode is enabled, the end of a transaction with master can be detected by the corresponding RXNE event signaling the last data transfer completion.
- In SPI transmit mode, user can check the BSY under timeout corresponding to the time necessary to complete the last data frame transaction. The timeout should be measured from TXE event signaling the last data frame transaction start (it is raised once the second bit transaction is ongoing). Either BSY becomes low normally or the timeout expires when the synchronization issue happens.

When upper workarounds are not applicable, the following sequence can be used to prevent the synchronization issue at SPI transmit mode:

1. Write last data to data register
2. Poll TXE until it becomes high to ensure the data transfer has started
3. Disable SPI by clearing SPE while the last data transfer is still ongoing
4. Poll the BSY bit until it becomes low
5. The BSY flag works correctly and can be used to recognize the end of the transaction.

*Note: This workaround can be used only when CPU has enough performance to disable SPI after TXE event is detected while the data frame transfer is still ongoing. It is impossible to achieve it when ratio between CPU and SPI clock is low and data frame is short especially. In this specific case timeout can be measured from TXE, while calculating fixed number of CPU clock periods corresponding to the time necessary to complete the data frame transaction.*

## 2.9.2 Corrupted last bit of data and/or CRC, received in Master mode with delayed SCK feedback

### Description

In receive transaction, in both I<sup>2</sup>S and SPI Master modes, the last bit of the transacted frame is not captured when the signal provided by internal feedback loop from the SCK pin exceeds a critical delay. The lastly transacted bit of the stored data then keeps the value from the pattern received previously. As a consequence, the last receive data bit may be wrong and/or the CRCERR flag can be unduly asserted in the SPI mode if any data under check sum and/or just the CRC pattern is wrongly captured.

In SPI mode, data are synchronous with the APB clock. A delay of up to two APB clock periods can thus be tolerated for the internal feedback delay. The I<sup>2</sup>S mode is more sensitive than the SPI mode since the SCK clock is not synchronized with the APB. In this case, the margin of the internal feedback delay is lower than one APB clock period.

The main factors contributing to the delay increase are low V<sub>DD</sub> level, high temperature, high SCK pin capacitive load and low SCK I/O output speed. The SPI communication speed has no impact.

### Workarounds

The following workaround can be adopted, jointly or individually:

- Decrease the APB clock speed.
- Configure the IO pad of the SCK pin to be faster.

The following table gives the maximum allowable APB frequency versus GPIOx\_OSPEEDR output speed control field setting for the SCK pin, at 30 pF of capacitive load.

**Table 5. Maximum allowable APB frequency at 30 pF load**

OSPEEDR [1:0] for SCK pin	Max. APB frequency for SPI mode [MHz]	Max. APB frequency for I2S mode [MHz]
Very high (11)	100	60
High (10)	85	45
Medium (01)	70	30
Low (00)	26	12

### 2.9.3 Wrong CRC calculation when the polynomial is even.

**Description:**

When the CRC is enabled, the CRC calculation will be wrong if the polynomial is even.

**Workaround:**

Use odd polynomial.

### 3 Revision history

**Table 6. Document revision history**

Date	Revision	Changes
20-Oct-2014	1	Initial release.
06-Feb-2017	2	Added: <ul style="list-style-type: none"><li>– <i>Section 2.1.10: In some specific cases, DMA2 data corruption occurs when managing AHB and APB2 peripherals in a concurrent way</i></li><li>– <i>Section 2.4.2: Corrupted last bit of data and/or CRC, received in Master mode with delayed SCK feedback</i></li><li>– <i>Section 2.9: SPI peripheral limitations</i></li></ul> Updated: <ul style="list-style-type: none"><li>– <i>Section 2.1.7: PB5 I/O limitation for externally applied voltage</i></li></ul>

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